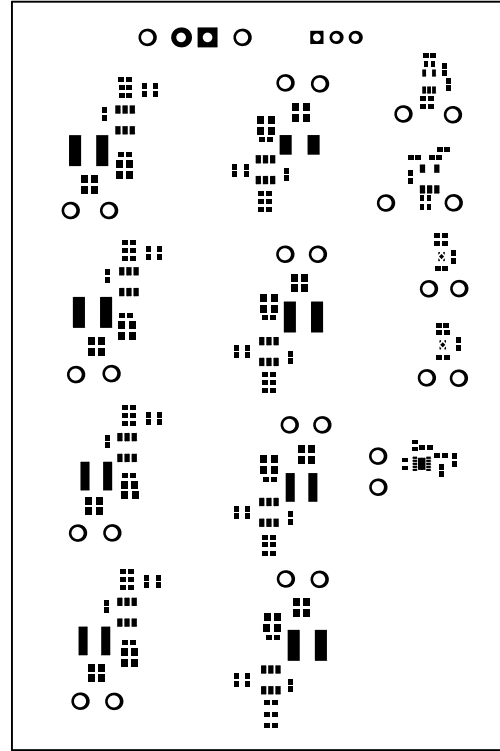
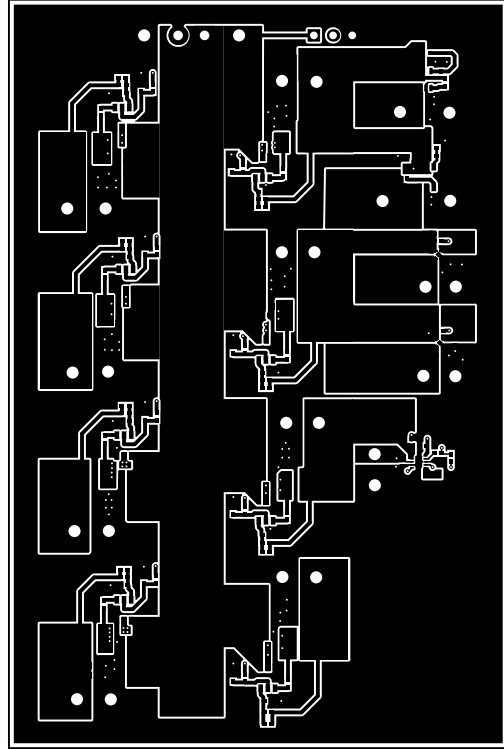


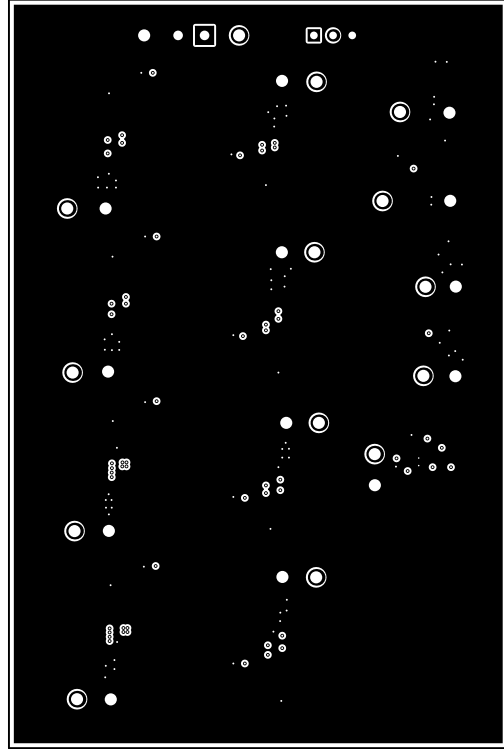
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 9/20/2017	5:07:47 PM	TEXAS INSTRUMENTS



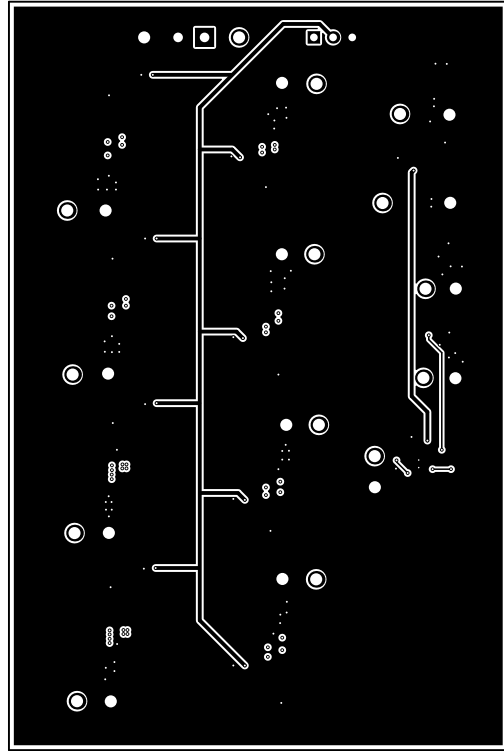
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 9/20/2017	5:07:49 PM	TEXAS INSTRUMENTS



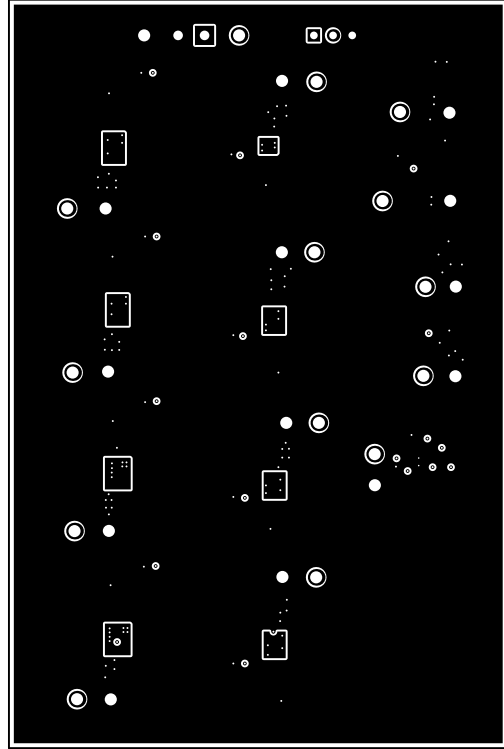
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 9/20/2017 5:07:50 PM	TEXAS INSTRUMENTS	



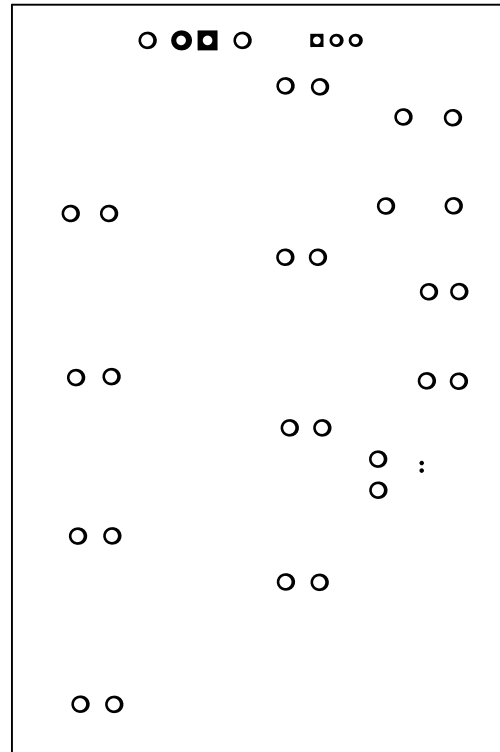
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 9/20/2017 5:07:51 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 9/20/2017 5:07:52 PM	TEXAS INSTRUMENTS	



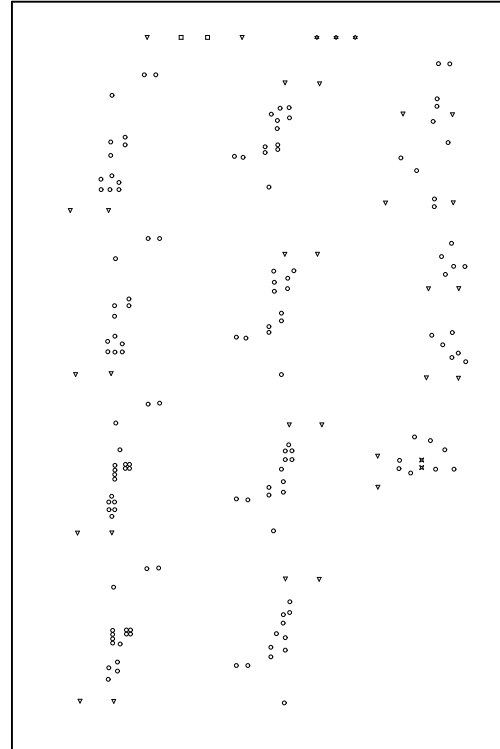
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 9/20/2017 5:07:54 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/20/2017 5:07:55 PM	TEXAS INSTRUMENTS	

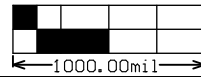


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 9/20/2017 5:07:56 PM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
⊗	2	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
○	140	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
☆	3	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
□	2	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
▽	28	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
175 Total							

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 9/20/2017 5:07:57 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21065A	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 9/20/2017 5:07:59 PM	TEXAS INSTRUMENTS	

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